LW G6CP

Advanced Power TOPLED®

Advanced Power TOPLED features a compact package with a wide brightness range and high luminous efficiency.

Applications

- Cluster, Button Backlighting
- Custom Tuning
- Interior Illumination (e.g. Ambient Map)

Features:

- Package: white SMT package, colorless clear silicone resin
- Chip technology: ThinGaN
- Typ. Radiation: 120° (Lambertian emitter)
- Color: Cx = 0.33, Cy = 0.33 acc. to CIE 1931 (• white)
- Optical efficacy: 46 lm/W
- Corrosion Robustness Class: 3B
- CRI: 80
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)

Ordering Information

Type	Luminous Intensity [1] I_F = 140 mA I_v	Ordering Code
LW G6CP-EAFA-JKQL-1	7.1 ... 14.0 cd	Q65110A8947

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min. max.	-40 °C 125 °C
Storage Temperature	T_{stg}	min. max.	-40 °C 125 °C
Junction Temperature	T_j	max.	150 °C
Junction Temperature for short time applications*	T_j	max.	175 °C
Forward Current T_S = 25 °C	I_F	min. max.	30 mA 250 mA
Surge Current t ≤ 10 µs; D = 0.005 ; T_S = 25 °C	I_{FS}	max.	750 mA
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV
Reverse current [2)]	I_R	max.	200 mA

*The median lifetime (L70/B50) for Tj =175°C is 100h.

Characteristics

I_F = 140 mA; T_S = 25 °C

Parameter	Symbol		Values
Chromaticity Coordinate [3]	Cx Cy	typ. typ.	0.33 0.33
Viewing angle at 50% I_V	2φ	typ.	120 °
Forward Voltage [4] I_F = 140 mA	V_F	min. typ. max.	2.90 V 3.30 V 4.10 V
Reverse voltage (ESD device)	$V_{R\ ESD}$	min.	45 V
Reverse voltage [2] I_R = 20 mA	V_R	max.	1.2 V
Color Rendering Index	CRI	typ.	80
Real thermal resistance junction/solderpoint [5]	$R_{thJS\ real}$	typ. max.	35 K / W 40 K / W

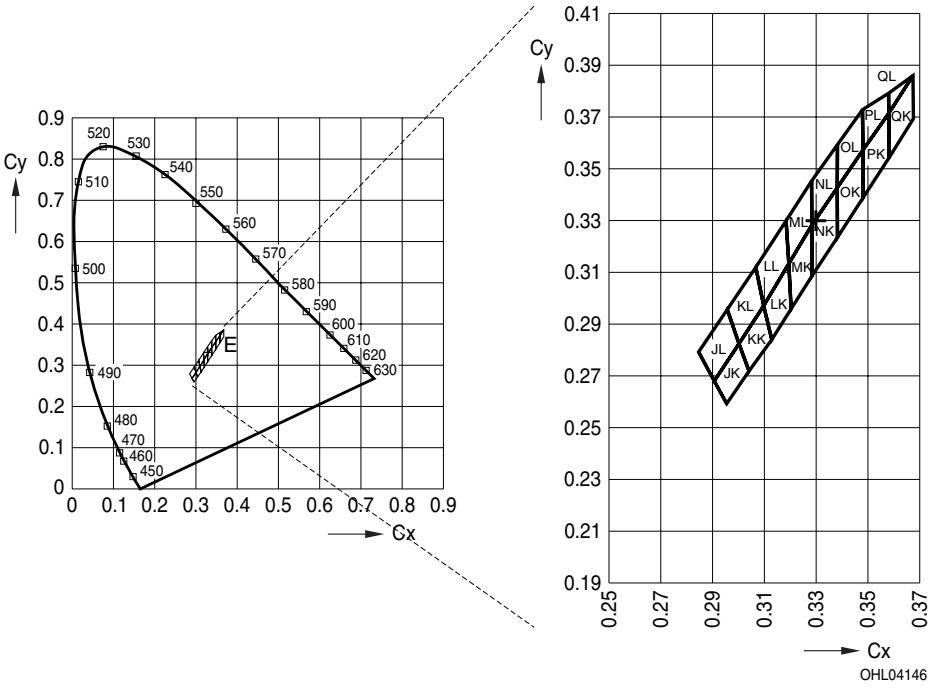
Brightness Groups

Group	Luminous Intensity [1] I_F = 140 mA min. I_v	Luminous Intensity [1] I_F = 140 mA max. I_v	Luminous Flux [6] I_F = 140 mA typ. Φ_V
EA	7.1 cd	9.0 cd	24.2 lm
EB	9.0 cd	11.2 cd	30.3 lm
FA	11.2 cd	14.0 cd	37.8 lm

Forward Voltage Groups

Group	Forward Voltage [4] I_F = 140 mA min. V_F	Forward Voltage [4] I_F = 140 mA max. V_F
4	2.90 V	3.20 V
5	3.20 V	3.50 V
6	3.50 V	3.80 V
7	3.80 V	4.10 V

Chromaticity Coordinate Groups [3)]



Color Chromaticity Groups [3)]

Group	Cx	Cy	Group	Cx	Cy	Group	Cx	Cy
JK	0.2960	0.2590	LK	0.3100	0.2970	NK	0.3288	0.3081
	0.2910	0.2680		0.3197	0.3131		0.3288	0.3282
	0.3005	0.2825		0.3205	0.2956		0.3386	0.3426
	0.3045	0.2715		0.3130	0.2840		0.3386	0.3235
JL	0.2910	0.2680	LL	0.3070	0.3120	NL	0.3288	0.3282
	0.2850	0.2790		0.3189	0.3302		0.3288	0.3453
	0.2960	0.2955		0.3197	0.3131		0.3386	0.3591
	0.3005	0.2825		0.3100	0.2970		0.3386	0.3426
KK	0.3045	0.2715	MK	0.3197	0.3131	OK	0.3386	0.3235
	0.3005	0.2825		0.3288	0.3282		0.3386	0.3426
	0.3100	0.2970		0.3288	0.3081		0.3484	0.3571
	0.3130	0.2840		0.3205	0.2956		0.3484	0.3388
KL	0.3005	0.2825	ML	0.3189	0.3302	OL	0.3386	0.3426
	0.2960	0.2955		0.3288	0.3452		0.3386	0.3591
	0.3070	0.3120		0.3288	0.3282		0.3484	0.3730
	0.3100	0.2970		0.3197	0.3131		0.3484	0.3571

Group	Cx	Cy
PK	0.3484	0.3388
	0.3484	0.3571
	0.3582	0.3715
	0.3582	0.3542
PL	0.3484	0.3571
	0.3484	0.3730
	0.3582	0.3792
	0.3582	0.3715

Group	Cx	Cy
QK	0.3582	0.3542
	0.3582	0.3715
	0.3680	0.3859
	0.3680	0.3695
QL	0.3582	0.3715
	0.3582	0.3792
	0.3680	0.3859
	0.3680	0.3859

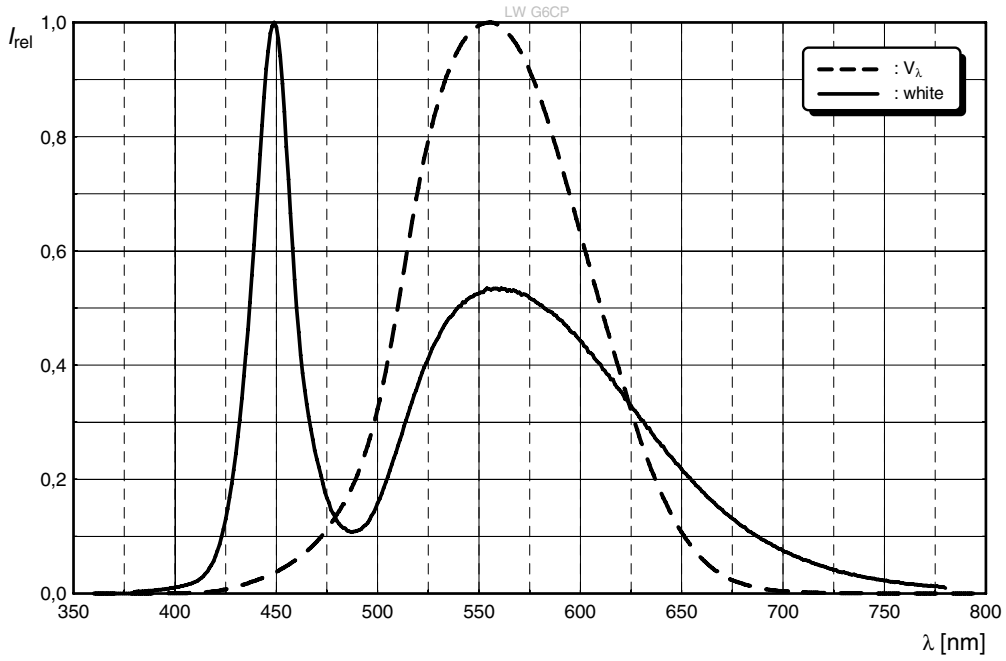
Group Name on Label

Example: EA-JK-4

Brightness	Color Chromaticity	Forward Voltage
EA	JK	4

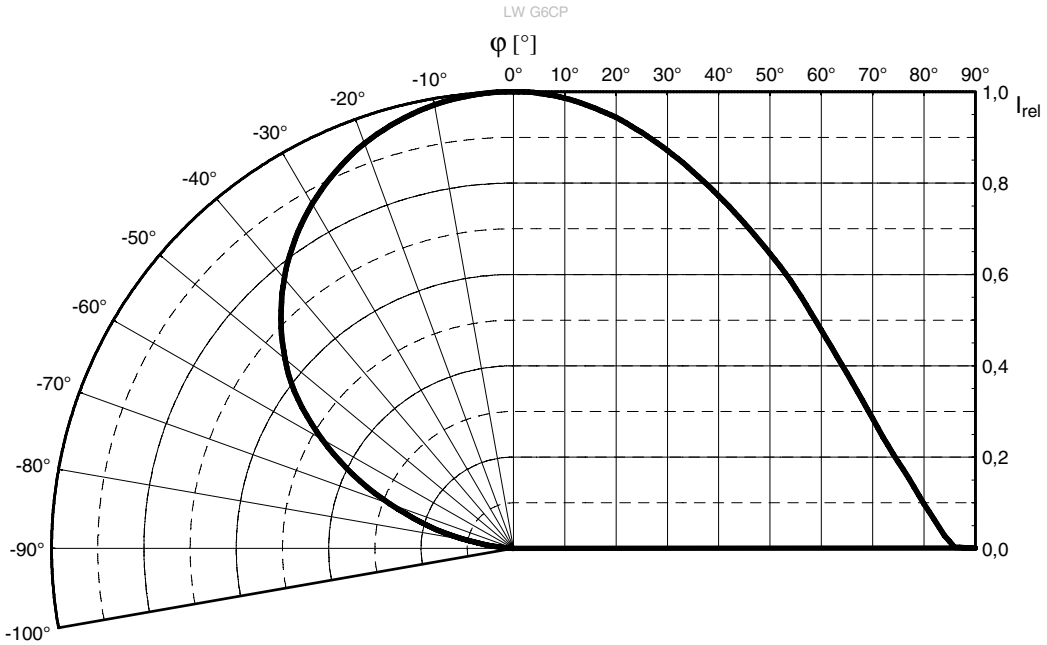
Relative Spectral Emission [6)]

$I_{rel} = f(\lambda)$; I_F = 140 mA; T_S = 25 °C



Radiation Characteristics [6)]

$I_{rel} = f(\phi)$; T_S = 25 °C



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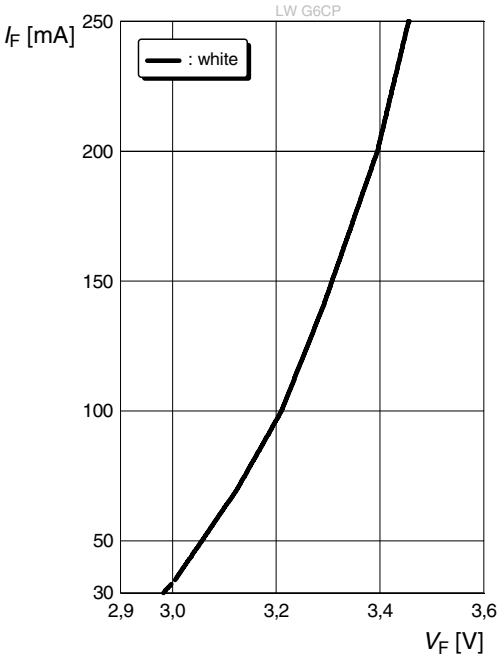
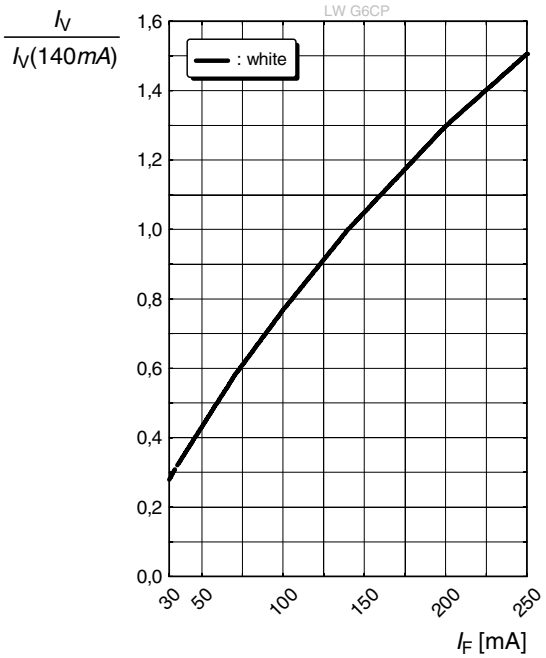
Forward current 6), 7)

$I_F = f(V_F)$; T_S = 25 °C



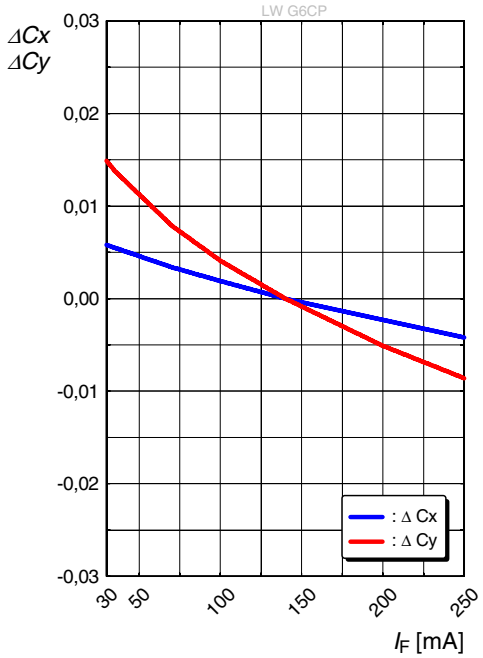
Relative Luminous Intensity 6), 7)

$I_v/I_v(140\ mA) = f(I_F)$; T_S = 25 °C



Chromaticity Coordinate Shift 6)

$\Delta Cx, \Delta Cy = f(I_F)$; T_S = 25 °C



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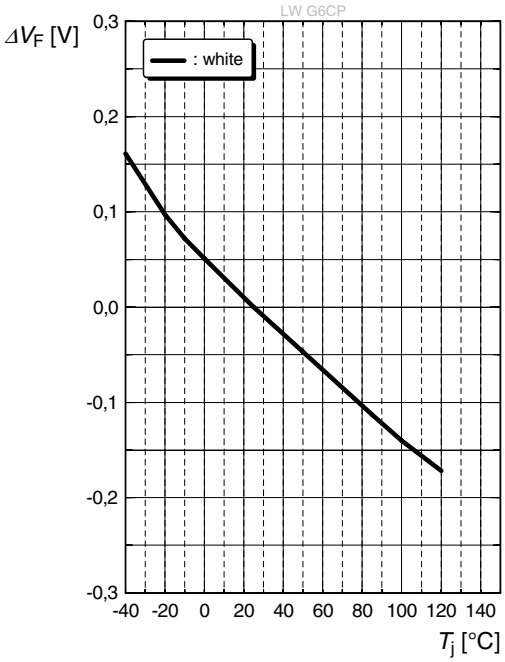
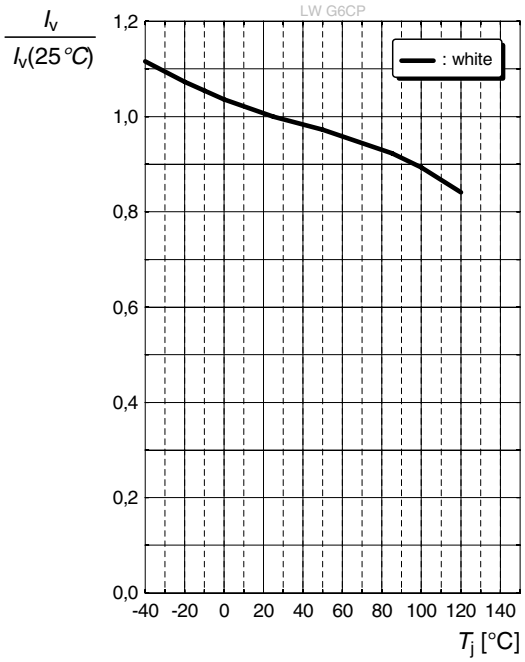
Forward Voltage [6]

$\Delta V_F = V_F - V_F(25\ °C) = f(T_j);\ I_F = 140\ mA$



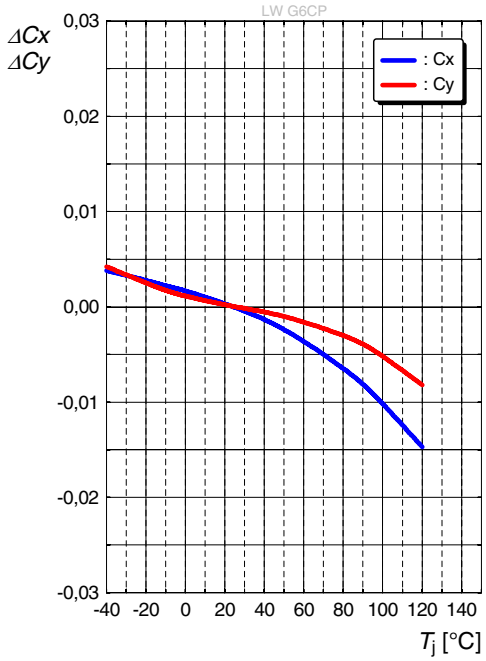
Relative Luminous Intensity [6]

$I_v/I_v(25\ °C) = f(T_j);\ I_F = 140\ mA$



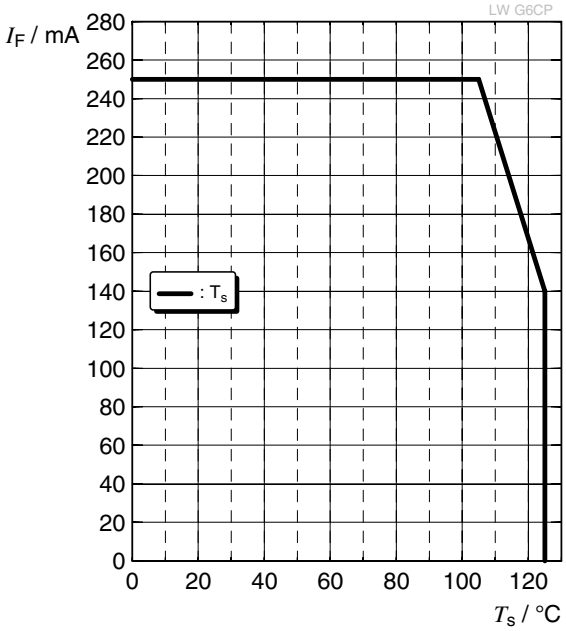
Chromaticity Coordinate Shift [6]

$\Delta Cx, \Delta Cy = f(T_j);\ I_F = 140\ mA$



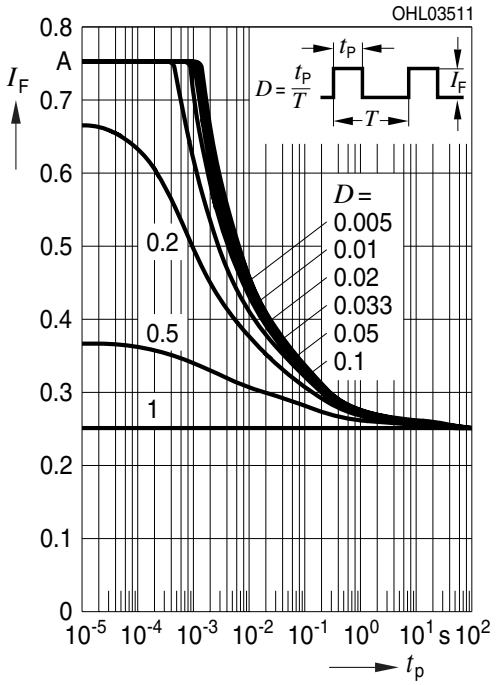
Max. Permissible Forward Current

$I_F = f(T)$



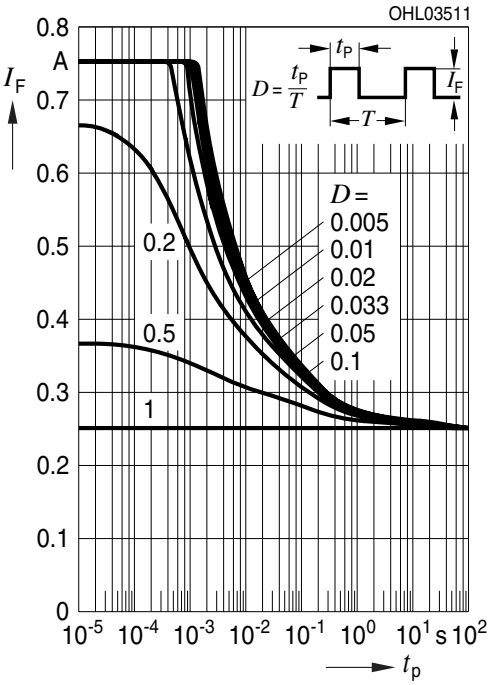
Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle; T_S = 25 °C

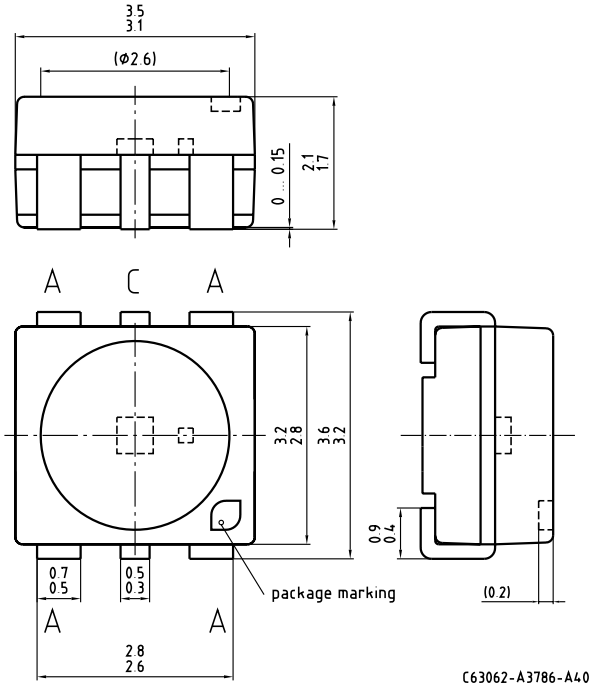


Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle; T_S = 85 °C

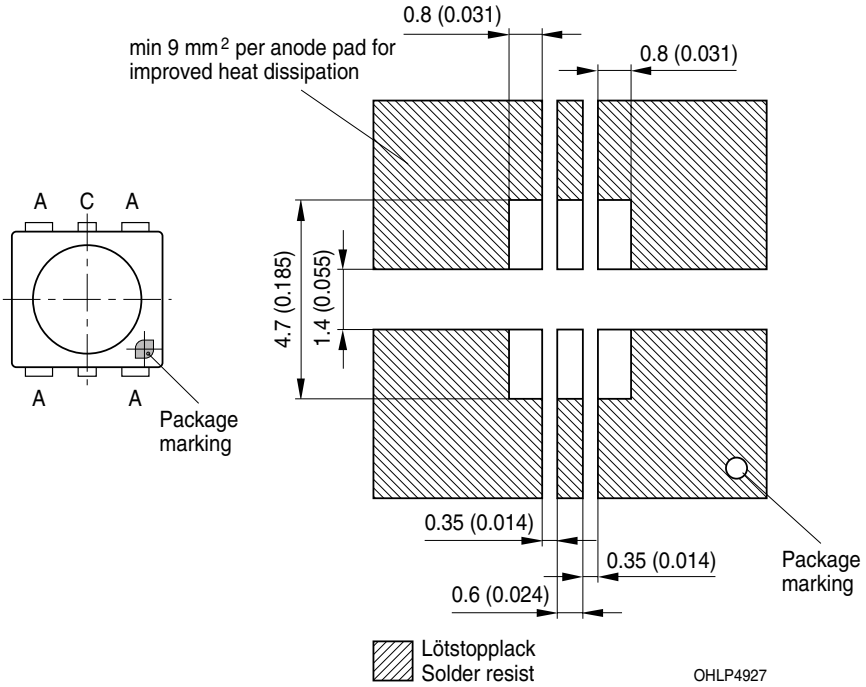


Dimensional Drawing [8)]



Approximate Weight:	40.0 mg
Package marking:	Anode
Corrosion test:	Class: 3B Test condition: 40°C / 90 % RH / 15 ppm H_2S / 14 days (stricter then IEC 60068-2-43)
ESD advice:	The device is protected by ESD device which is connected in parallel to the Chip.

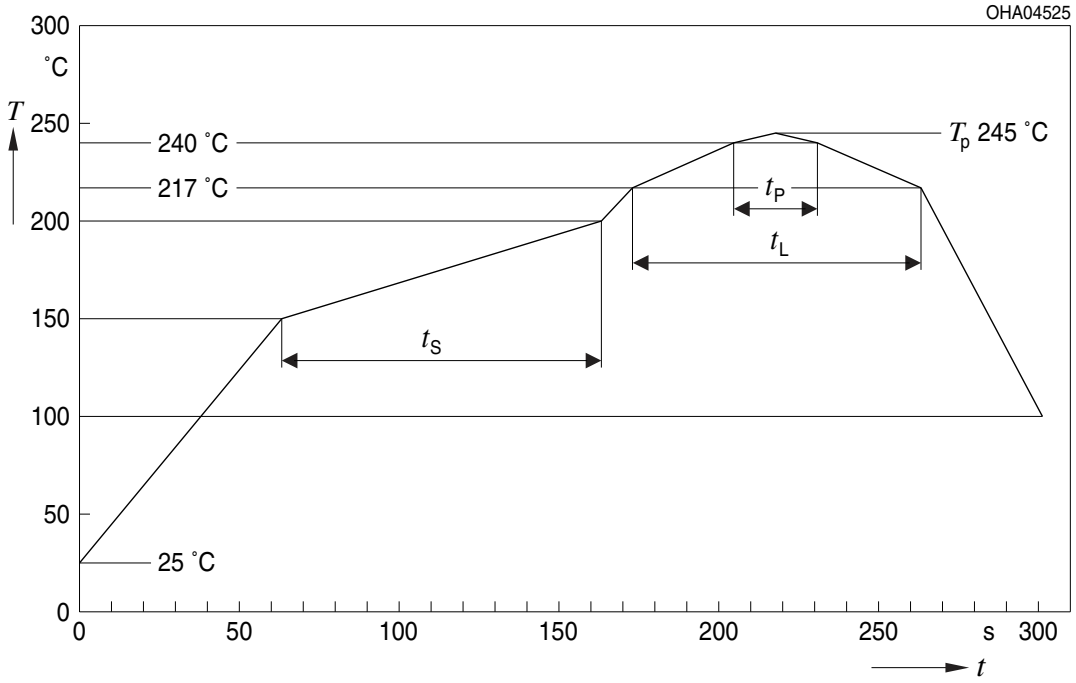
Recommended Solder Pad [8)]



For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

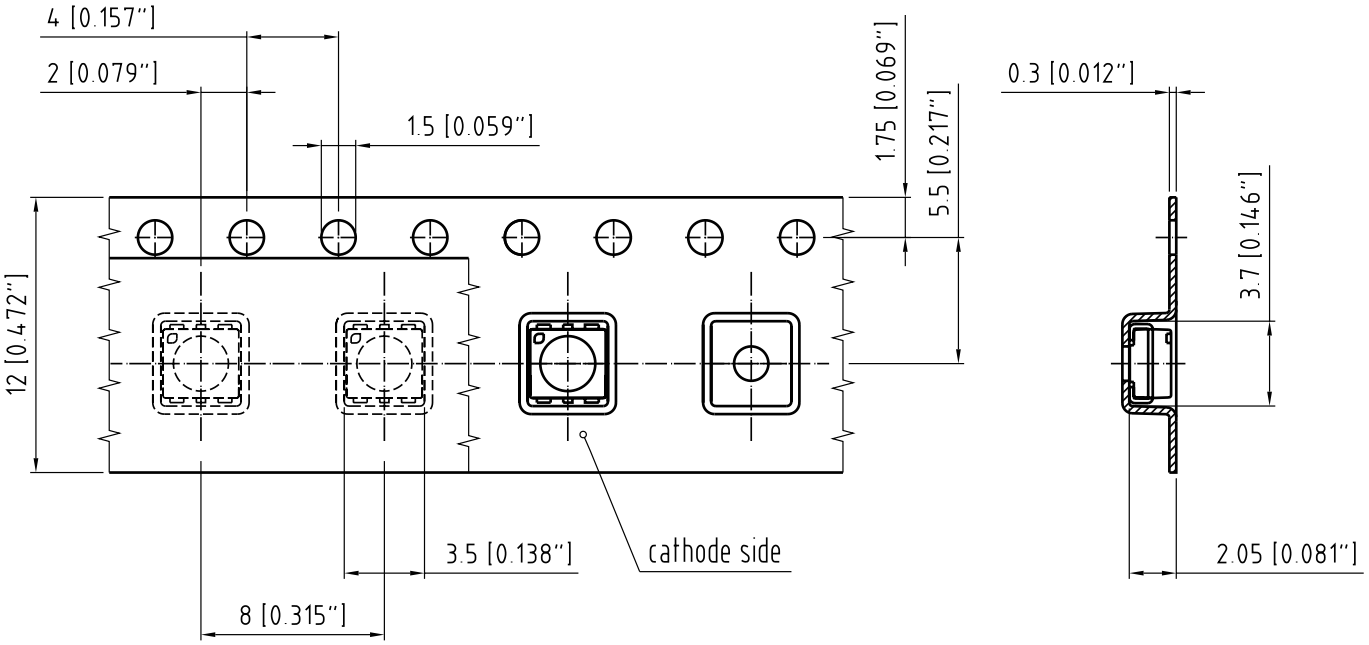
Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_S T_{Smin} to T_{Smax}	t_S	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_P			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_P		245	260	°C
Time within 5 °C of the specified peak temperature T_P - 5 K	t_P	10	20	30	s
Ramp-down rate* T_P to 100 °C			3	6	K/s
Time 25 °C to T_P				480	s

All temperatures refer to the center of the package, measured on the top of the component
* slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

Taping [8)]



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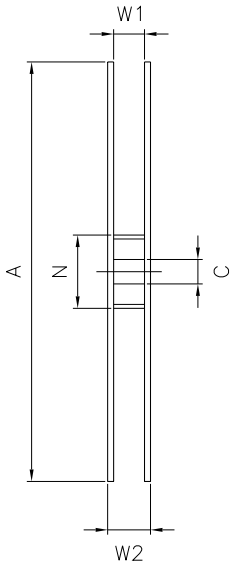
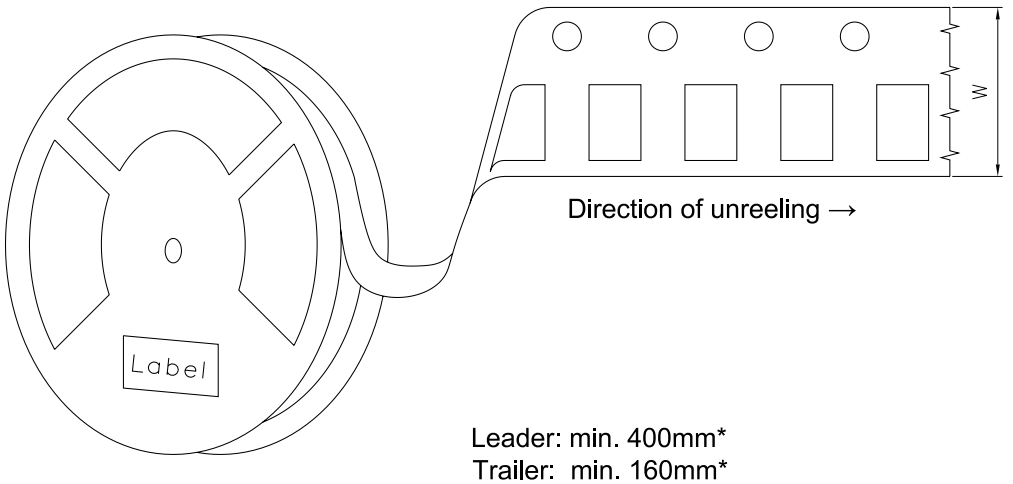
Tape and Reel [9)]



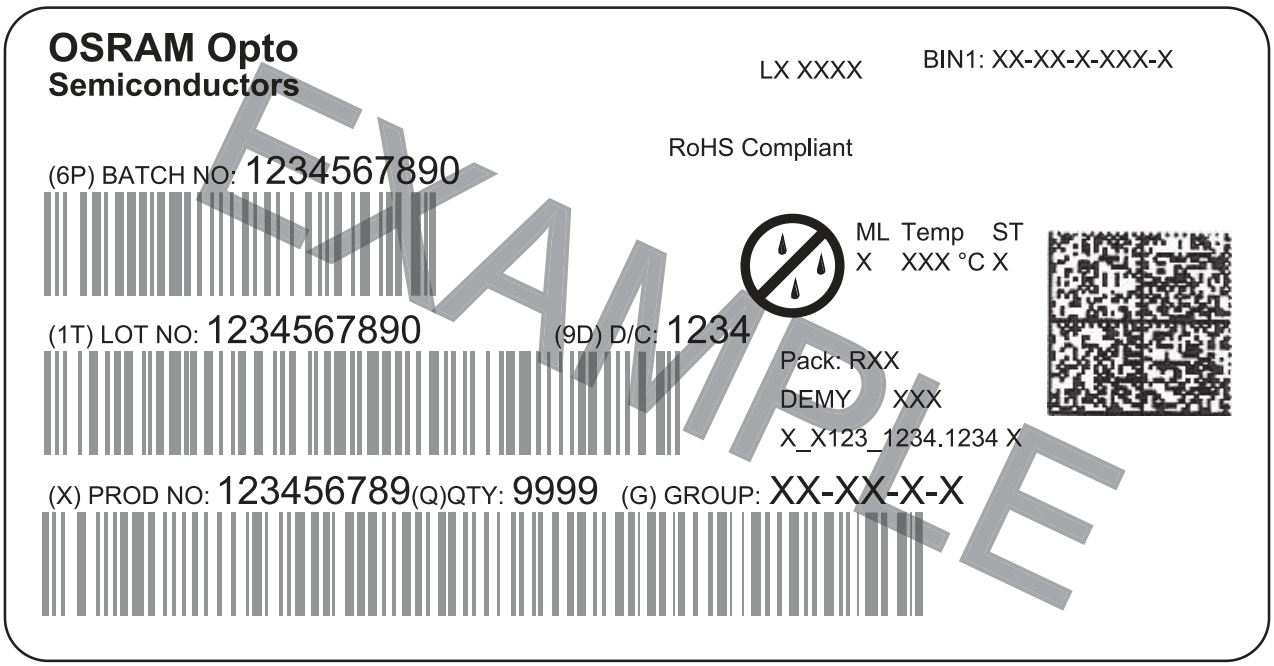


Leader: min. 400mm*
Trailer: min. 160mm*
*)Dimensions acc. to IEC 60286-3; EIA 481-E

Reel dimensions [mm]

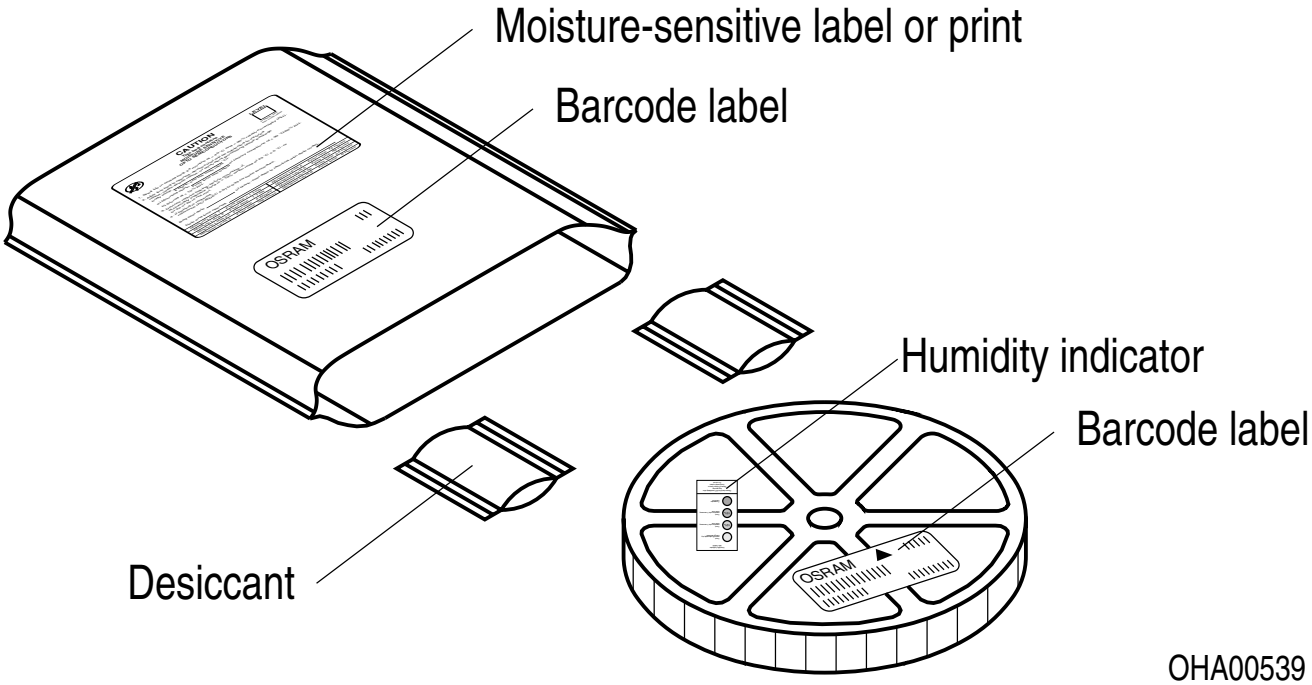
A	W	N_{min}	W_1	$W_{2\,max}$	Pieces per PU
180 mm	12 + 0.3 / - 0.1	60	12.4 + 2	18.4	1000

Barcode-Product-Label (BPL)



OHA04563

Dry Packing Process and Materials [8)]



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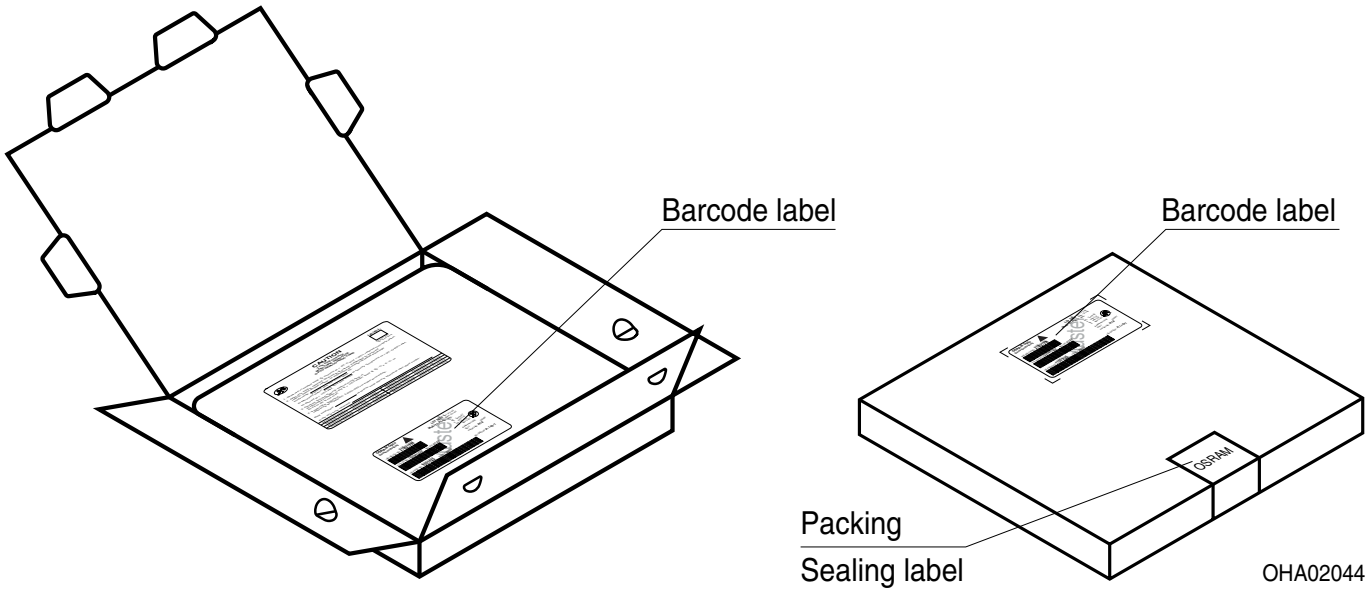
Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Schematic transportation box [8)]



Dimensions of transportation box in mm

Width	Length	Height
195 ± 5 mm	195 ± 5 mm	30 ± 5 mm

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes

Disclaimer

Attention please!
The information describes the type of component and shall not be considered as assured characteristics.
Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.
For information on the types in question please contact our Sales Organization.
If printed or downloaded, please find the latest version on the OSRAM OS webside.

Packing
Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.
By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product safety devices/applications or medical devices/applications
OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

In case Buyer – or Customer supplied by Buyer– considers using OSRAM OS components in product safety devices/applications or medical devices/applications, Buyer and/or Customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and Buyer and /or Customer will analyze and coordinate the customer-specific request between OSRAM OS and Buyer and/or Customer.

Glossary

1) **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of k = 3).

2) **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.

3) **Chromaticity coordinate groups:** Chromaticity coordinates are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±0.005 and an expanded uncertainty of ±0.01 (acc. to GUM with a coverage factor of k = 3).

4) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).

5) **Thermal Resistance:** Rth max is based on statistic values (6σ).

6) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.

8) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.

9) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

Version	Date	Change
1.6	2018-12-20	Max. Permissible Forward Current Diagramm Recommended Solder Pad

Published by OSRAM Opto Semiconductors GmbH
Leibnizstraße 4, D-93055 Regensburg

EU RoHS and China RoHS compliant product

此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，不含有毒有害物质或元素。